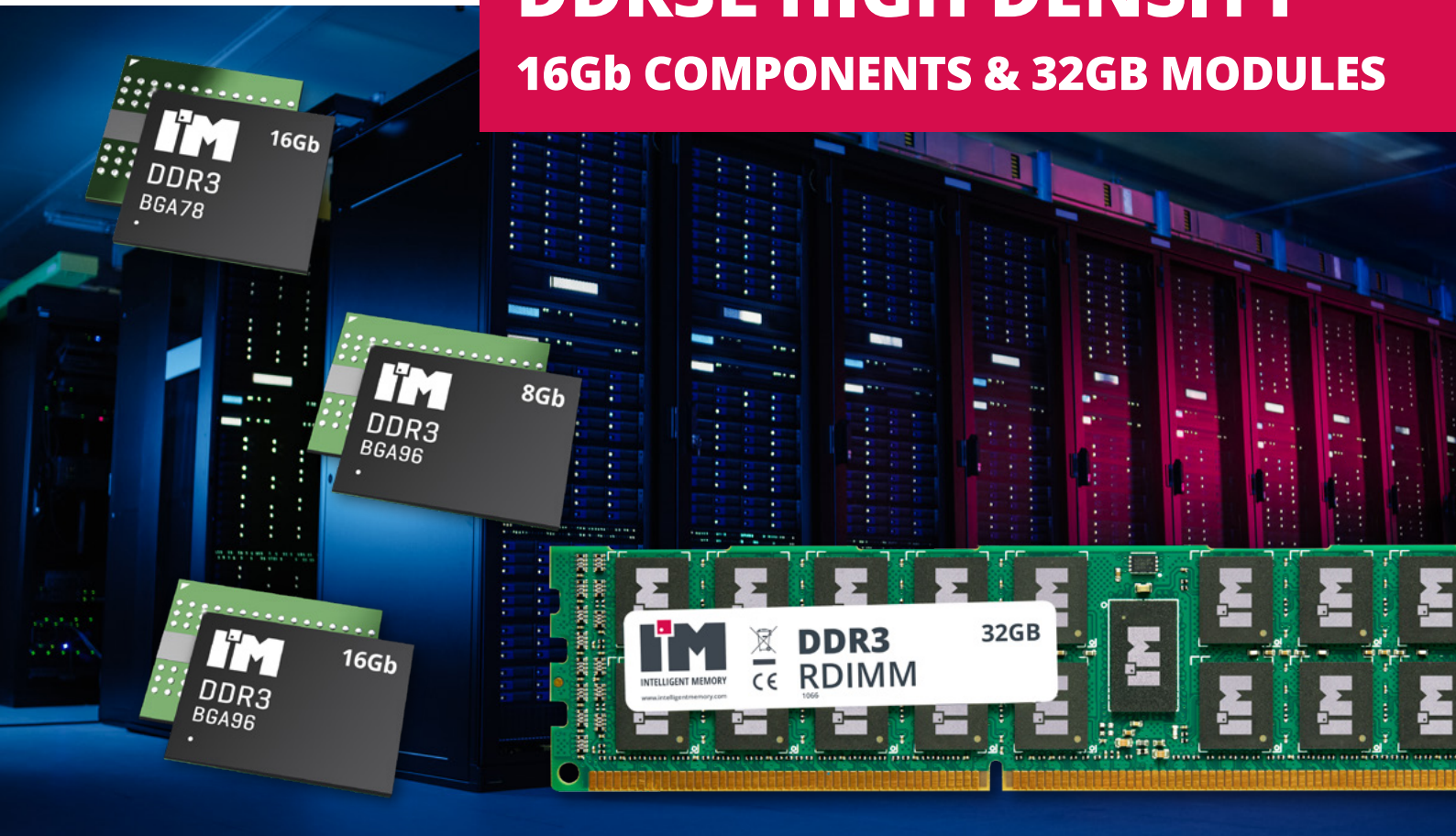


DDR3L HIGH DENSITY

16Gb COMPONENTS & 32GB MODULES



To cope with the challenge of achieving double memory density without the necessity of two separate sets of control wires, IM developed a unique way to manufacture 8Gb DDR3 Single Chip Select components with the existing DRAM process technologies.

From the application's point of view, it will see these components work like a monolithic device. IM's 8Gb Single Chip Select components are compatible with the JEDEC pinout of monolithic devices and provide the simplest path to upgrading applications using DDR3 DRAM.

Based on IM's 8Gb Single Chip Select methodology, IM also developed the higher memory density of 16Gb DDR3 components for applications demanding a higher memory capacity.

For DDR3 16Gb components, Intelligent Memory also offers a Two Chip Select x16 configuration available with speeds up to DDR3L-1866 in both Commercial and Industrial Temperature options. Besides components, IM introduced the very first 16GB UDIMM and SODIMM memory modules, based on their 8Gb Single Chip Select components. The modules follow the 2 ranks JEDEC specification.



For more information or to request samples, please visit us at www.intelligentmemory.com

You may also contact our sales team directly at sales@intelligentmemory.com

October 2024
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DDR3L HIGH DENSITY 16Gb COMPONENTS & 32GB MODULES

Key Features

- Longevity for 7 years+ and long-term support
- Commercial and Industrial Temperature grades as standard
- **Components**
 - Available in x4, x8, and x16 organizations with 1-CS and 2-CS
 - BGA components ensure long-term reliability
 - Speeds up to DDR3L-2133
- **Modules**
 - 16GB UDIMM & SO-DIMM modules (ECC optional)
 - Speeds up to PC3-14900
 - “Plug-and-Play” modules compatible with JEDEC standards
 - 32GB RDIMM modules

Applications

- Aerospace & Defense
- Automation Systems
- Data Storage Systems
- Embedded Systems
- Energy & Utilities
- Industrial Automation
- Industrial PCs
- Manufacturing Control Systems
- Medical Devices & Imaging
- Military & Aerospace Systems
- Networking Equipment
- Telecommunications
- Test & Measurement Equipment

Product List DDR3L 8Gb Components

Part No.	Density	Org.	Chip Select	Voltage	Package	Speed	Temperature
IM8G08D3FFBG-(125/107/093)(I)	8Gb	1Gx8	1-CS	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G16D3FFBG-(125/107/093)(I)	8Gb	512Mx16	1-CS	1.35V (1.5V)	FBGA 96	1600/1866/2133	Comm./Ind.
IM8G04D3FFDG-(125/107/093)(I)	8Gb	2Gx4	2-CS	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G08D3FFDG-(125/107/093)(I)	8Gb	1Gx8	2-CS	1.35V (1.5V)	FBGA 78	1600/1866/2133	Comm./Ind.
IM8G16D3FFDG-(125/107/093)(I)	8Gb	512Mx16	2-CS	1.35V (1.5V)	FBGA 96	1600/1866/2133	Comm./Ind.

Product List DDR3L 16Gb Components

Part No.	Density	Org.	Chip Select	Voltage	Package	Speed	Temperature
IMAG16D3FFDG-(125/107)(I)	16Gb	1Gx16	2-CS	1.35V (1.5V)	FBGA 96	1600/1866	Comm./Ind.

Product List DDR3L 16GB SODIMM Memory Modules

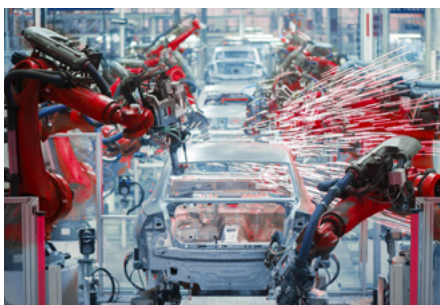
Part No.	Density	Org.	Rank	Voltage	Form Factor	Speed	Temperature
IMM2G64D3LSOD8AG-F(125/107)(I)	16GB SODIMM	2Gx64	2	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.
IMM2G72D3LSOD8AG-F(125/107)(I)	16GB ECC SODIMM	2Gx72	2	1.35V (1.5V)	204 Pin	1600/1866	Comm./Ind.

Product List DDR3L 16GB UDIMM Memory Modules

Part No.	Density	Org.	Rank	Voltage	Form Factor	Speed	Temperature
IMM2G64D3LDUD8AG-F(125/107)(I)	16GB UDIMM	2Gx64	2	1.35V (1.5V)	240 Pin	1600/1866	Comm./Ind.
IMM2G72D3LDUD8AG-F(125/107)(I)	16GB ECC UDIMM	2Gx72	2	1.35V (1.5V)	240 Pin	1600/1866	Comm./Ind.

Product List DDR3L 32GB RDIMM Memory Modules

Part No.	Density	Org.	Rank	Voltage	Form Factor	Speed	Temperature
IMM4G72D3RDQ4AG-F18(I)	32GB RDIMM	4Gx72	4	1.5V	240 Pin	1066	Comm./Ind.



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